2SA1700

Rev.E May.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

WR0585 ṂṂꝉ SQS ᴁṀɥ s ǁ ᒉ Silicon PNP transistor in a TO-252 Plastic Package.

/ Features

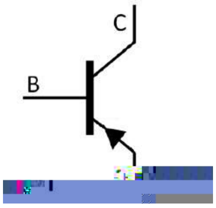
ہ` Ѵ ɔ ᴙ ɩ ǁ Ḅ￼ὣ ≩ ɬ ớ ɩ ゝ ɑ پ ϡ PELW ʿH

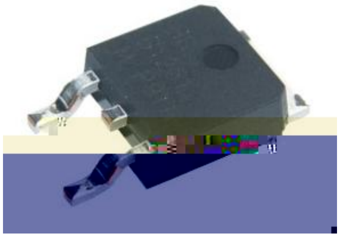
High breakdown voltage, adoption of MBIT process excellent h_{FE} linearity

[redacted]

Ȝ ⌊ ԇ ہ ᴙ ἰ Ʊ

High voltage driver applications.



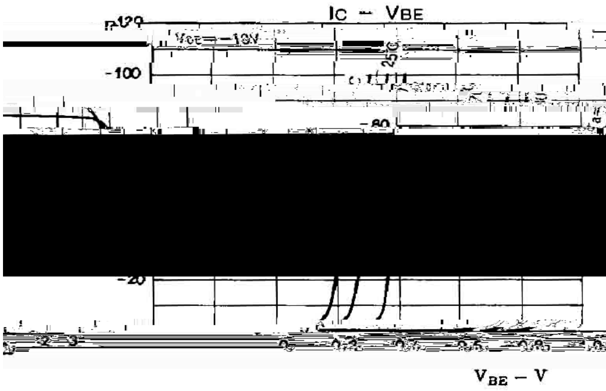


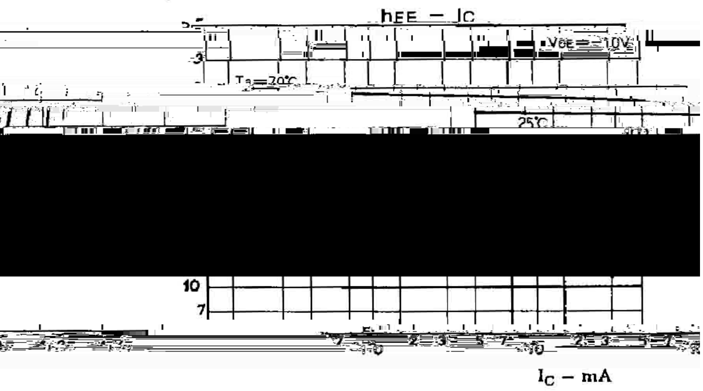
PIN1 χ Base PIN 2,4 χ Collector PIN 3 χ Emitter

/ h_{FE} Classifications & Marking

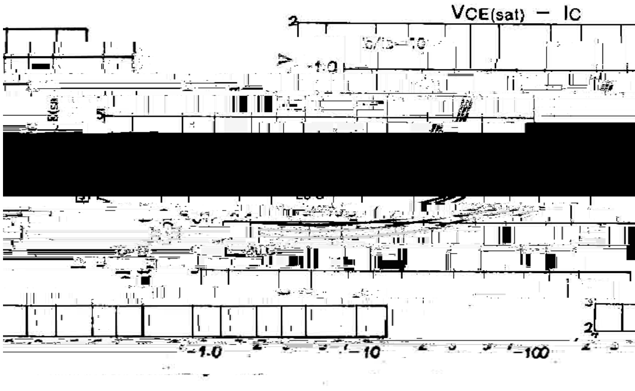
v ῼ Parameter	ɥ ᴺ Symbol	ῼӪ Rating	D Ʉ Unit
Collector to Base Voltage	V_{CBO}	-400	V

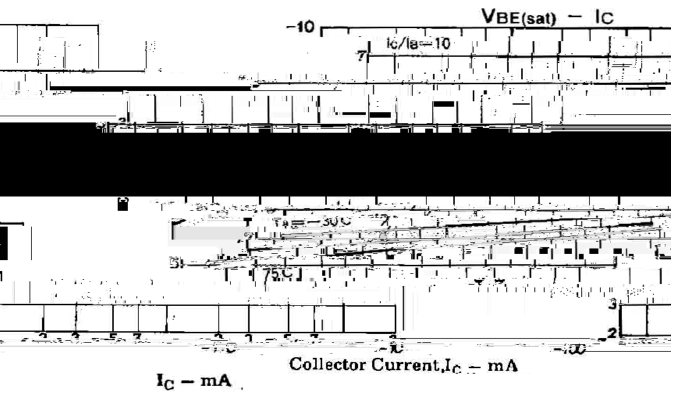
/ Electrical Characteristic Curve



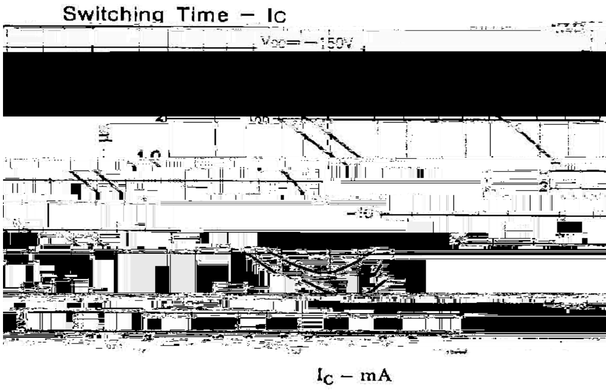


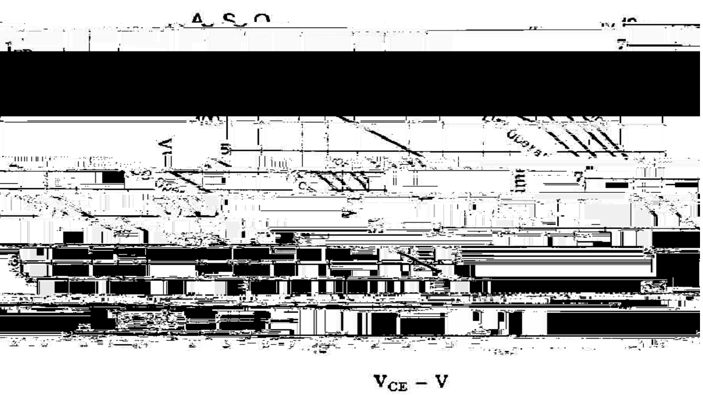
[redacted]



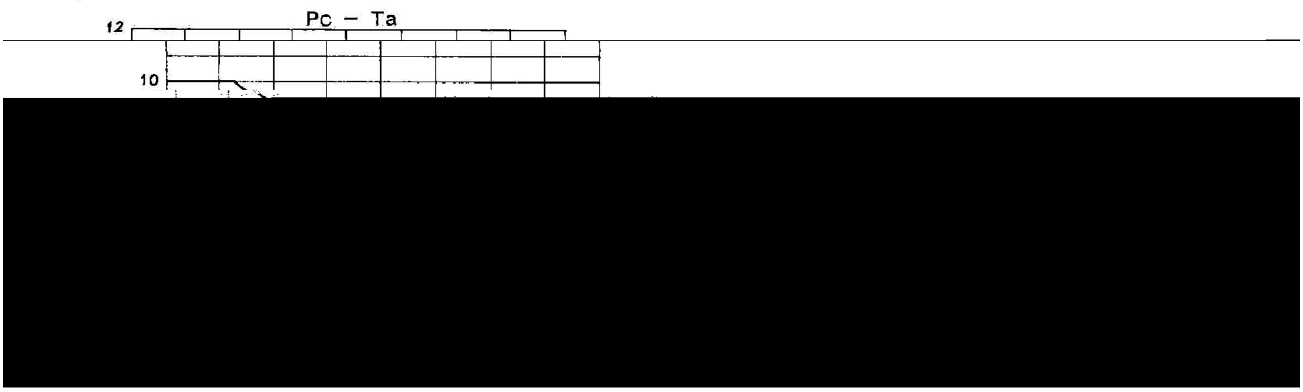


[redacted]



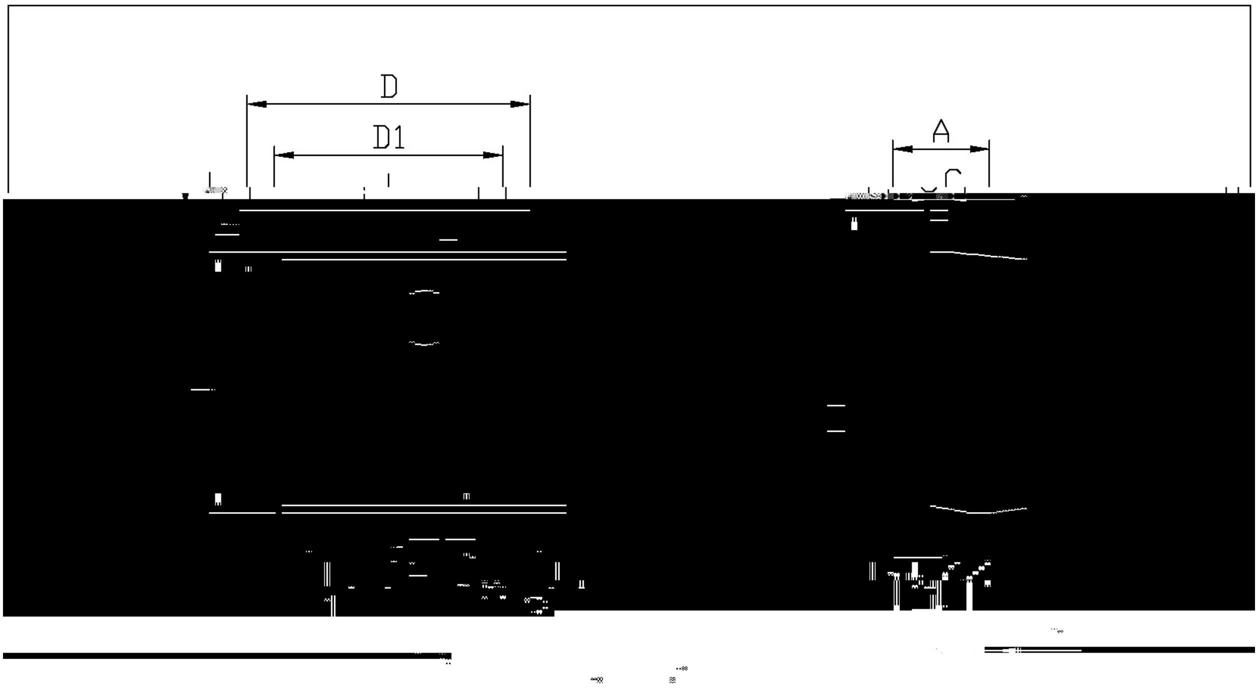


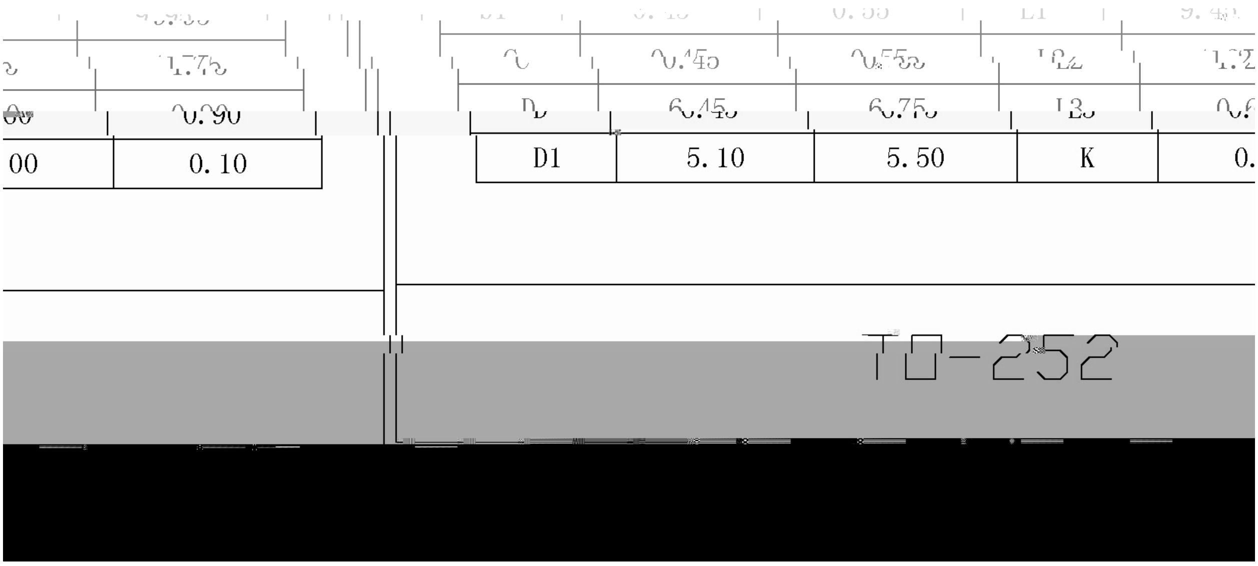
[redacted]



[redacted]

/ Package Dimensions



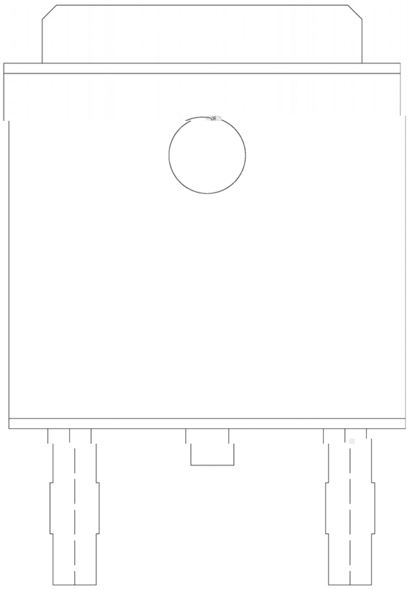


[illegible]	1.775
[illegible]	0.90
00	0.10

C	0.45	0.55	L2	1.72
D	6.45	6.75	L3	0.
D1	5.10	5.50	K	0.

TO-252

/ Marking Instructions



[illegible] χ

BR χ [illegible]

A1700 χ [illegible]

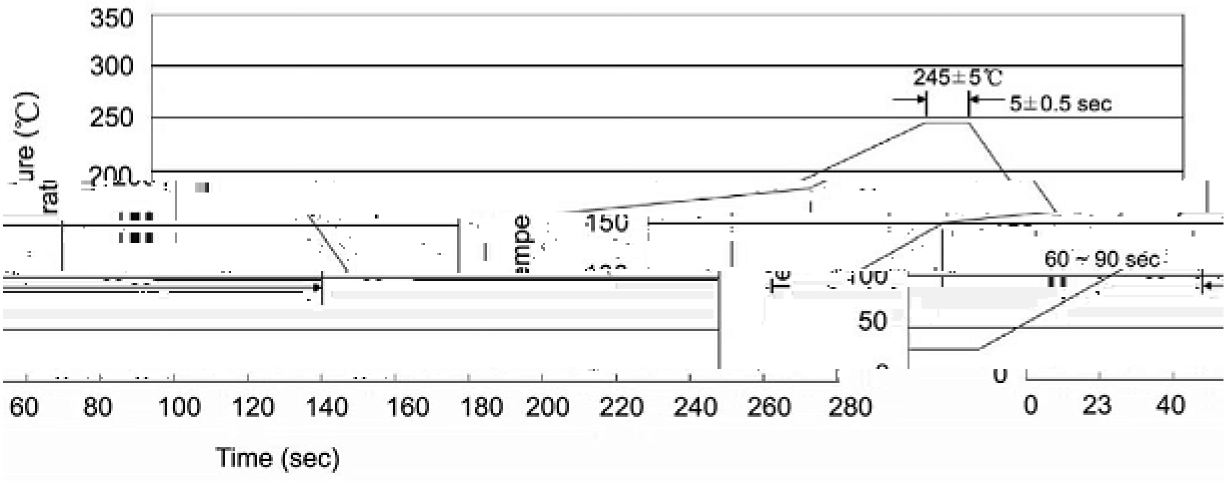
D: [illegible] h_{FE} [illegible]

---- χ [illegible]

Note:

BR: A13( )Tj22[illegible]Company[illegible]

(　　) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ	Note:
1　ا̊ ♬ □ ẙ 25 Ḱ 150 ƚ ı ̀H ڑ 60 Ḱ 90sec;	1.Preheating:25~150 ƚ , Time:60~90sec.
2　Ś Ӫ □ ẙ 245 ° 5 ƚ ı ̀H ڑ ʿY ʎ ㅒ 5 ° 0.5sec;	2.Peak Temp.:245 ° 5 ƚ , Duration:5 ° 0.5sec.
3　ì ˙ Ɣ ˛ ɔ ه ẙ ㅒ 2 Ḱ 10 ƚ /sec.	3. Cooling Speed: 2~10 ƚ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ẙ χ 260 ° 5 ƚ	̀H ڑ χ 10 ° 1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

ɷ ̀ γ Ŀ / REEL

Package Type	Units	Dimension	(unit mm^3)